



Patterning at
nanoscale:
mCP, NIL and
stenciling



Micro-530

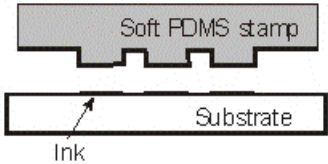
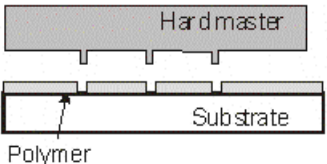
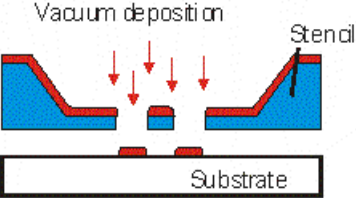
Emerging Nanopatterning Methods

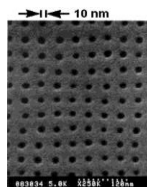
(Replication)

Soft-lithography

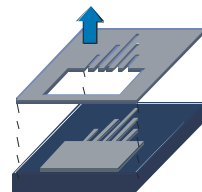
Nanoimprint lithography

Nanostencil lithography

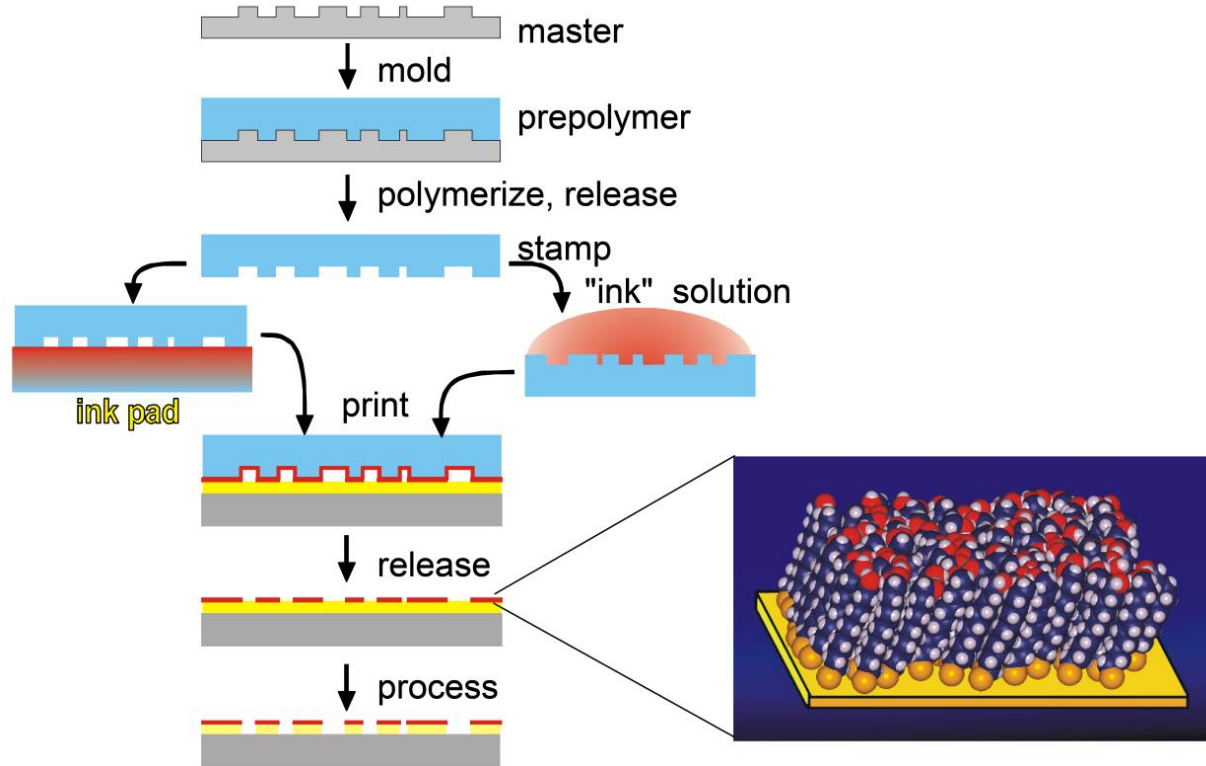
Ink delivery molecules, wet <i>soft-contact</i>	Thermo-mechanical, nano-imprinting, <i>hard contact</i>	Local deposition stencil, vacuum <i>no contact</i>
		



10 nm
Candidate for
Integrated Circuit



Microcontact Printing (μ CP)

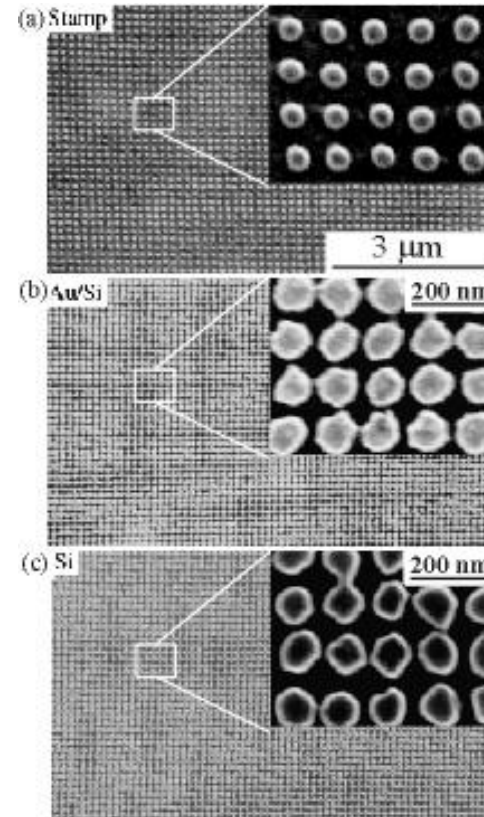


Microcontact Printing

High-resolution μ CP:

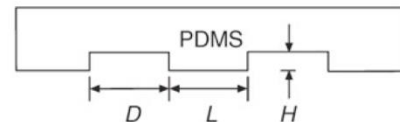
- a) Scanning electron micrograph of a stamp with 60 nm dots.
- b) The corresponding gold dots fabricated by printing and etching were slightly broadened due to ink diffusion and substrate roughness.
- c) The gold pattern served as a mask to etch the bare regions 250 nm deep into the underlying silicon by reactive ion etching.

<http://zurich.ibm.com>

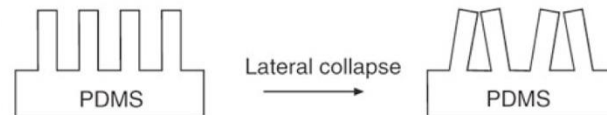


Microcontact Printing

- Possible problems and limitations
- Aspect ratio of stamp features
- Lateral collapse
- Sagging



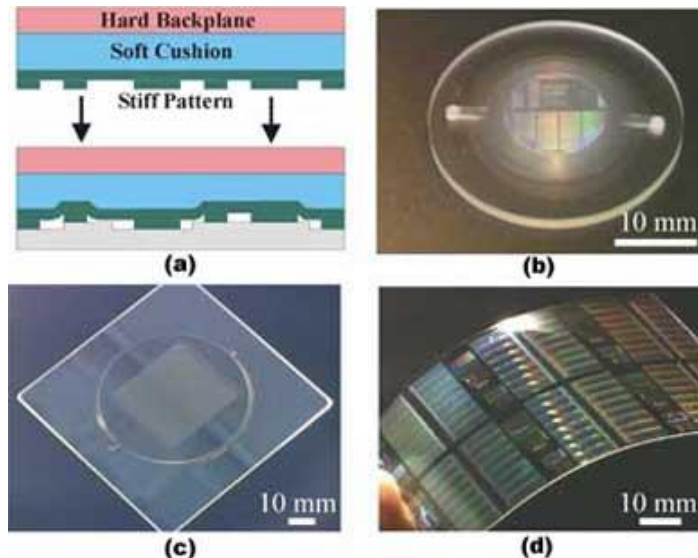
(Optimal aspect ratio: $0.5 < H/L < 5$, $H/D > 0.05$)



Microcontact Printing

Examples of layered hybrid stamps:

- a) Scheme of trilayer stamp (hard backplane, elastomeric cushion, hard polymer) showing improved adaptation to an uneven substrate
- b) Trilayer stamp with 270 nm features
- c) Bilayer stamp with 5 μm features on a 125 mm glass plate
- d) Example of a two layer, thin film stamp composed of a 100 μm glass backplane and a 30 μm polymer film with 270 nm features.



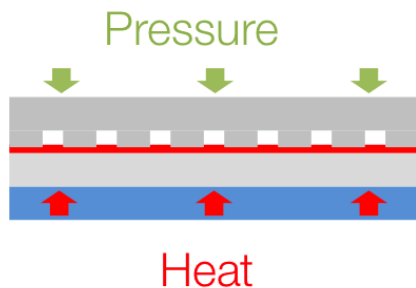
[From B. Michel, H. Schmid, Macromolecules 33 (2000) 3042].

Nano-Imprint Lithography



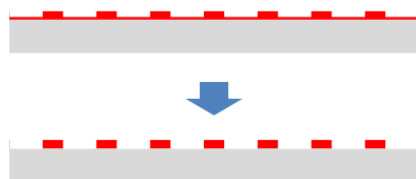
Imprint stack preparation

Stamp (or mold), Resist, Substrate,
Chuck



Imprinting

Pressure / temperature / time profile



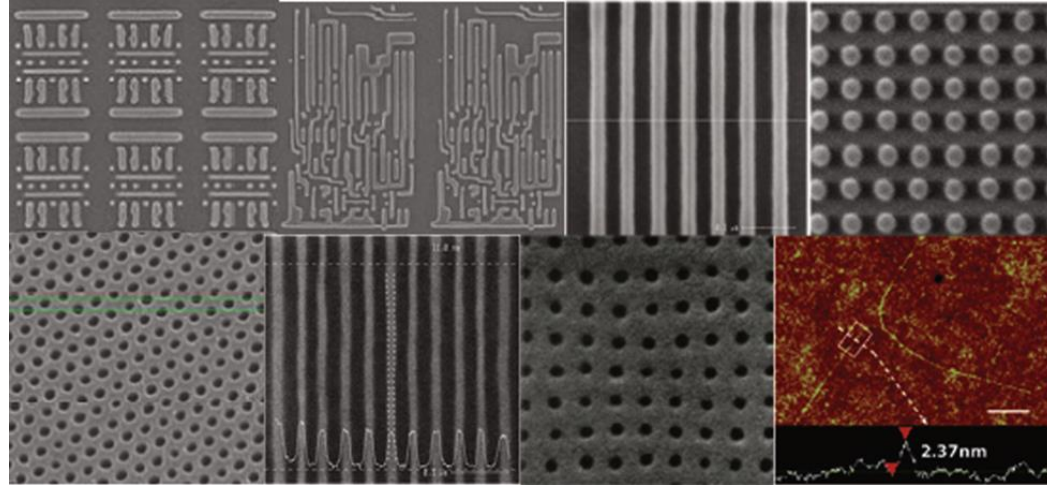
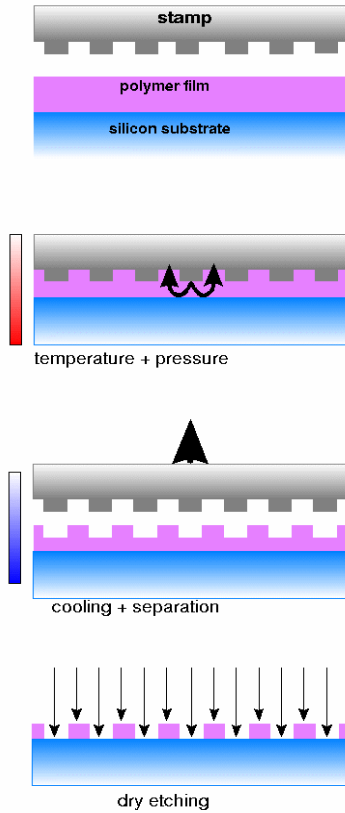
Separation

Temp control

Residual layer etch

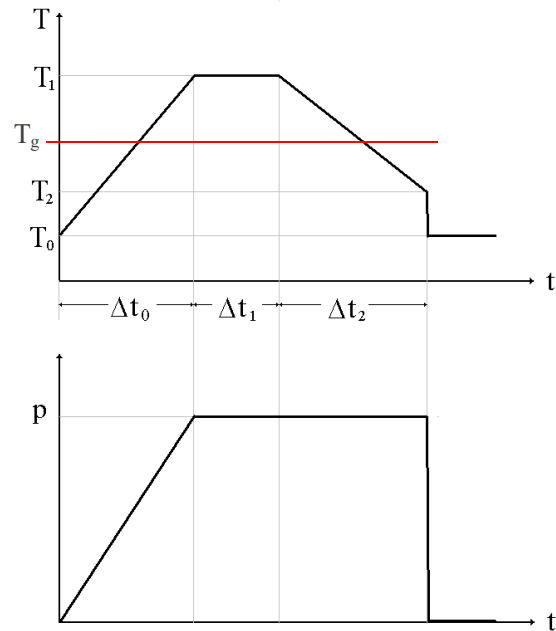
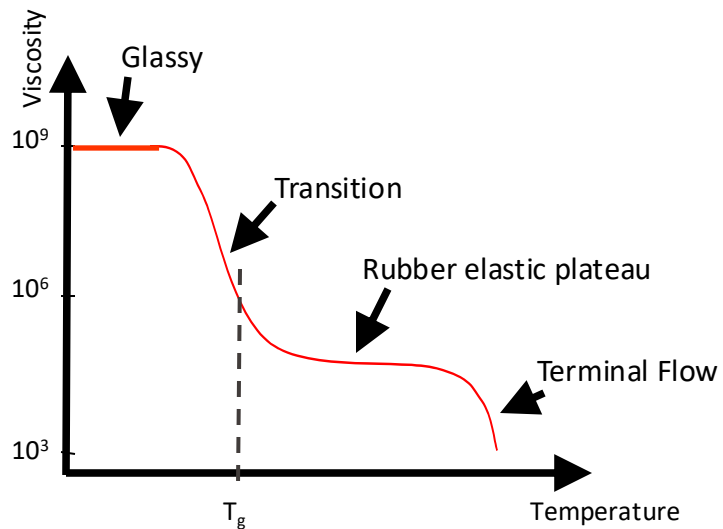
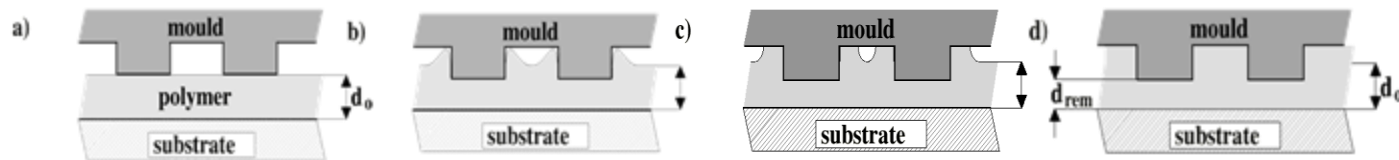
Remove thin resist layer by O₂ plasma

Nano-Imprint Lithography

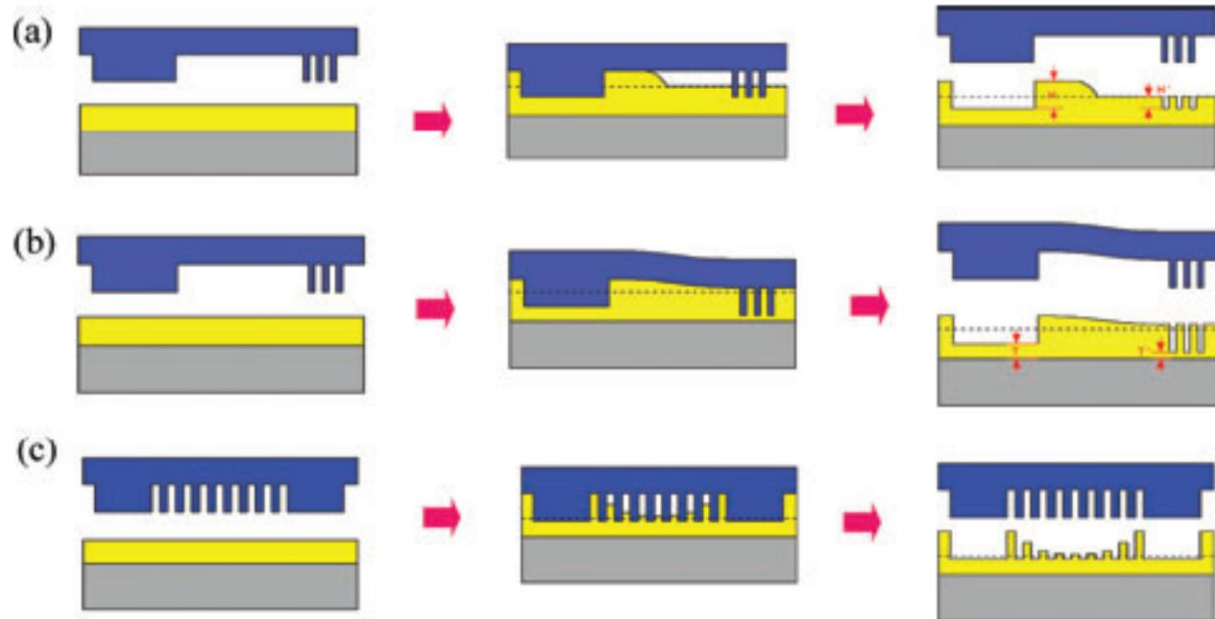


S. Chou et al. *Science* 5 April 1996: Vol. 272 no. 5258 pp. 85-87

Nanoimprint Process Model



Issues with thermal NIL

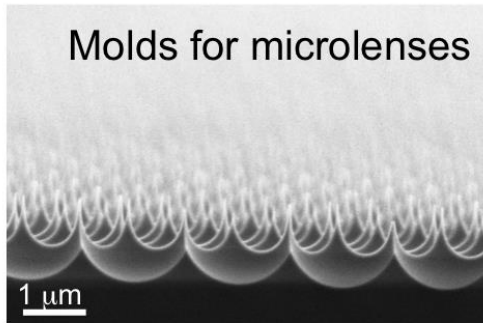
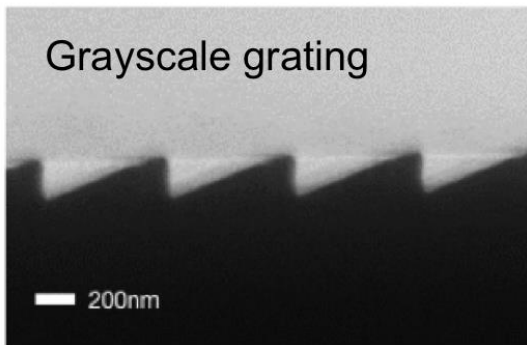
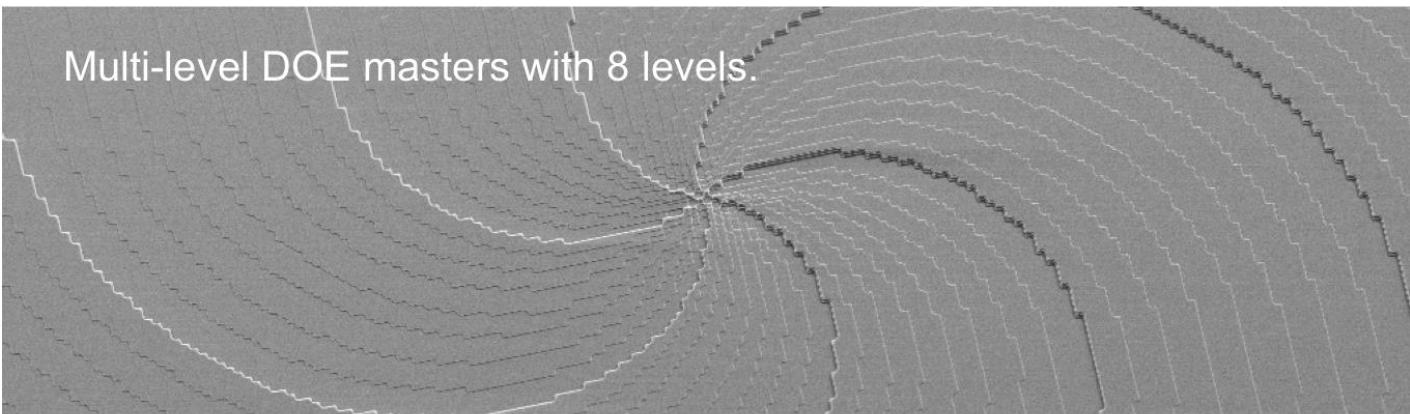


NIL examples

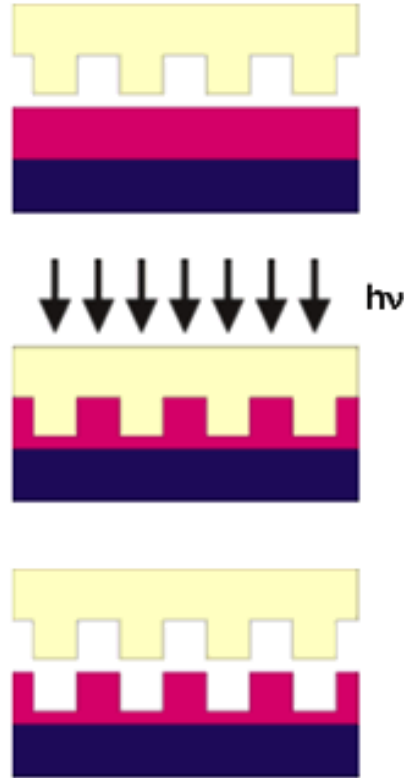
- Master stamp is costly
- Replicate master in working stamp
- Use working stamp for substrate imprinting and for mass fabrication
- Working stamp can be Nickel, Polymer, etc.

<https://www.nilt.com/>

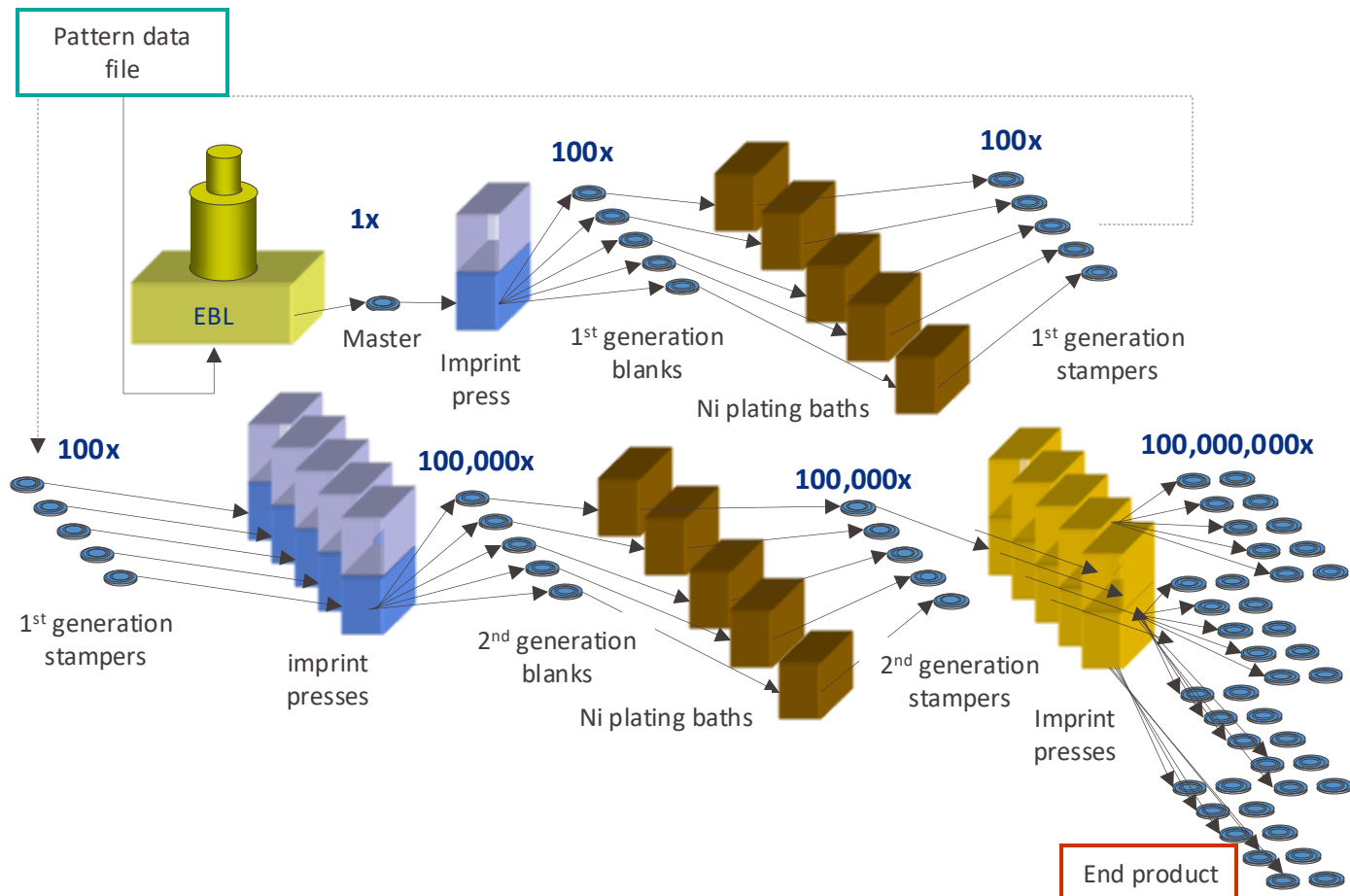
NIL examples



- UV nanoimprint based on liquid polymer

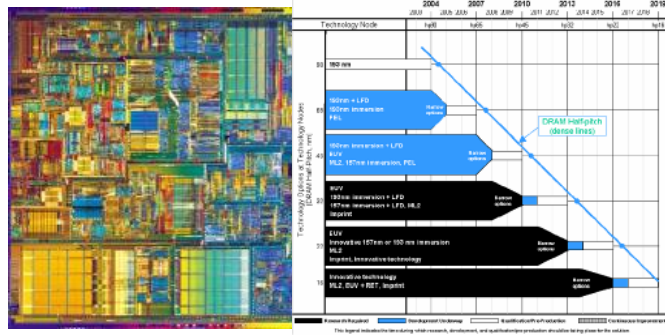


NIL in Mass Production

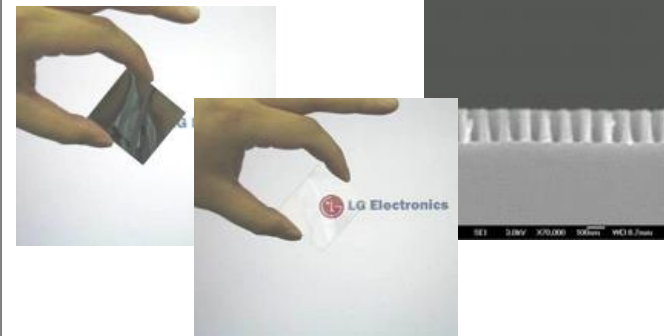


Nanopatterning – Main NIL Applications

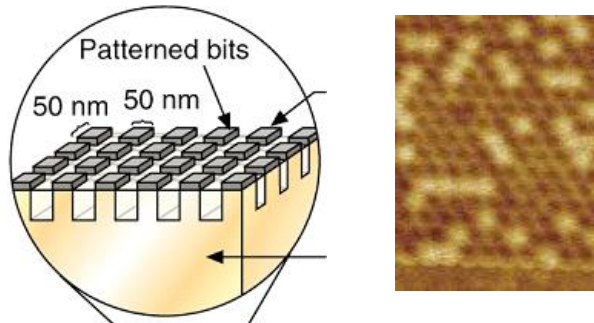
High End Microelectronic Chips



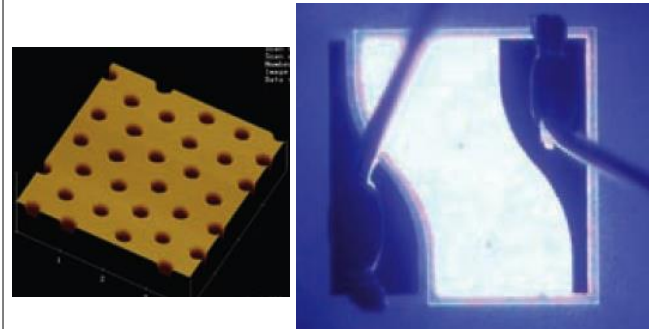
Wire Grid Polarizer



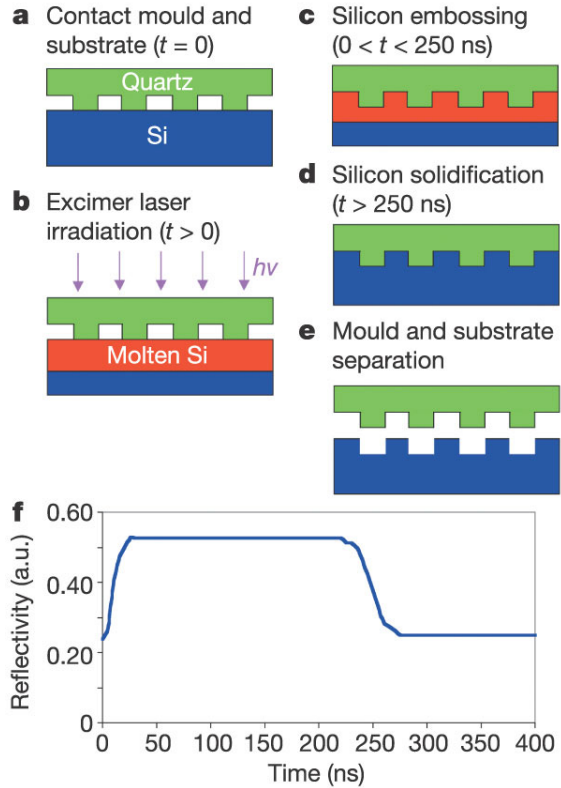
Patterned Magnetic Media



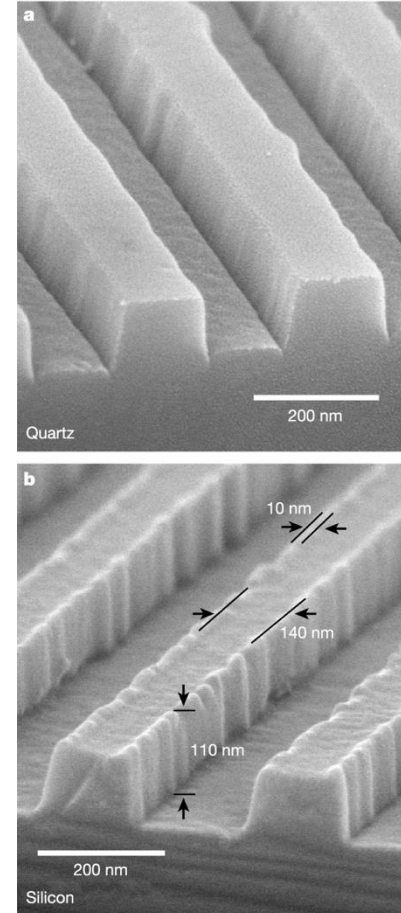
High Brightness LEDs



Direct printing into silicon



Stephen Y. Chou, Chris Keimel and Jian Gul Nature 417, 835-837(20 June 2002)





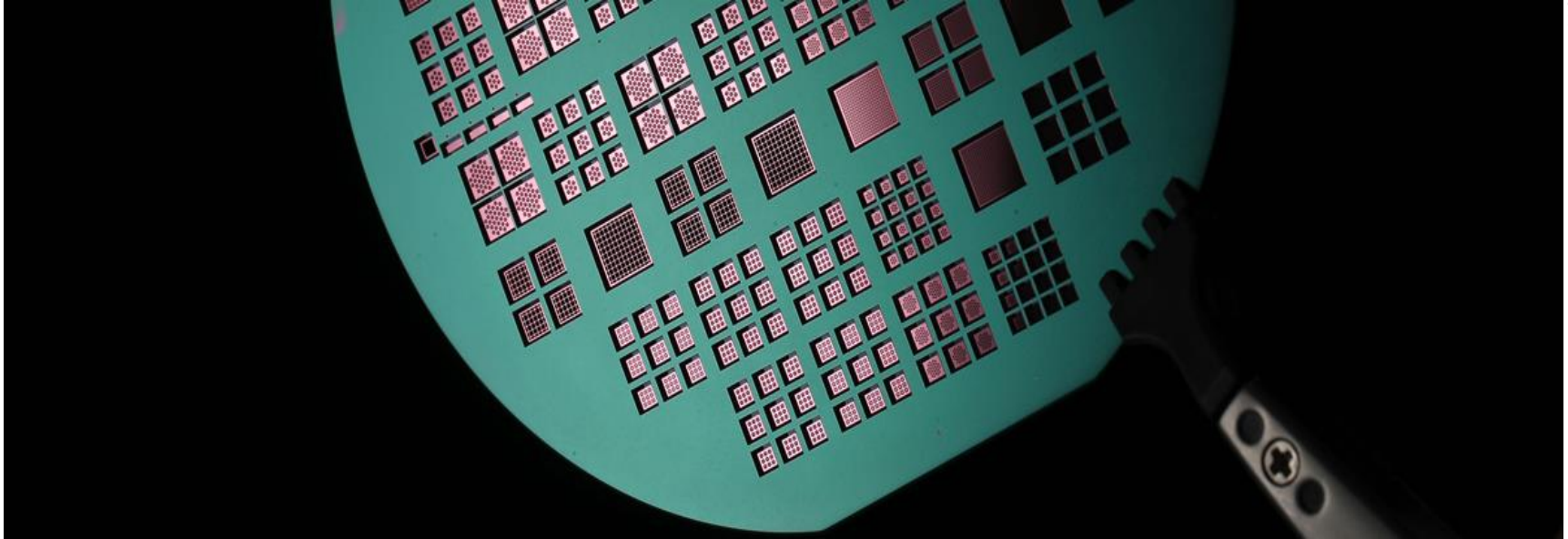
Patterning at nanoscale: Nanostencil Lithography

Micro-530

Stencil lithography (cartoon)



- Patterning without photoresist
- Very small ($<100\text{nm}$)
- Very large (mm)
- Vacuum clean
- Deposition
- Etching
- Implantation



Challenges:

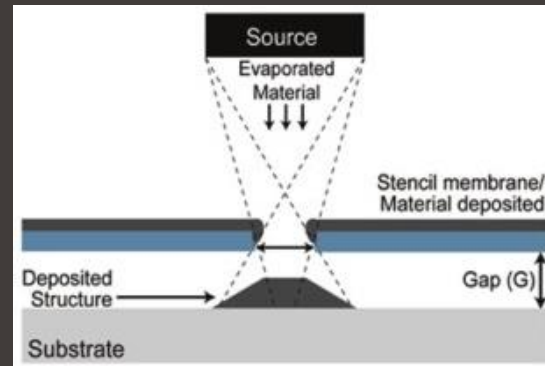
- Gap
- Blurring
- Membrane stability
- Alignment

Opportunities:

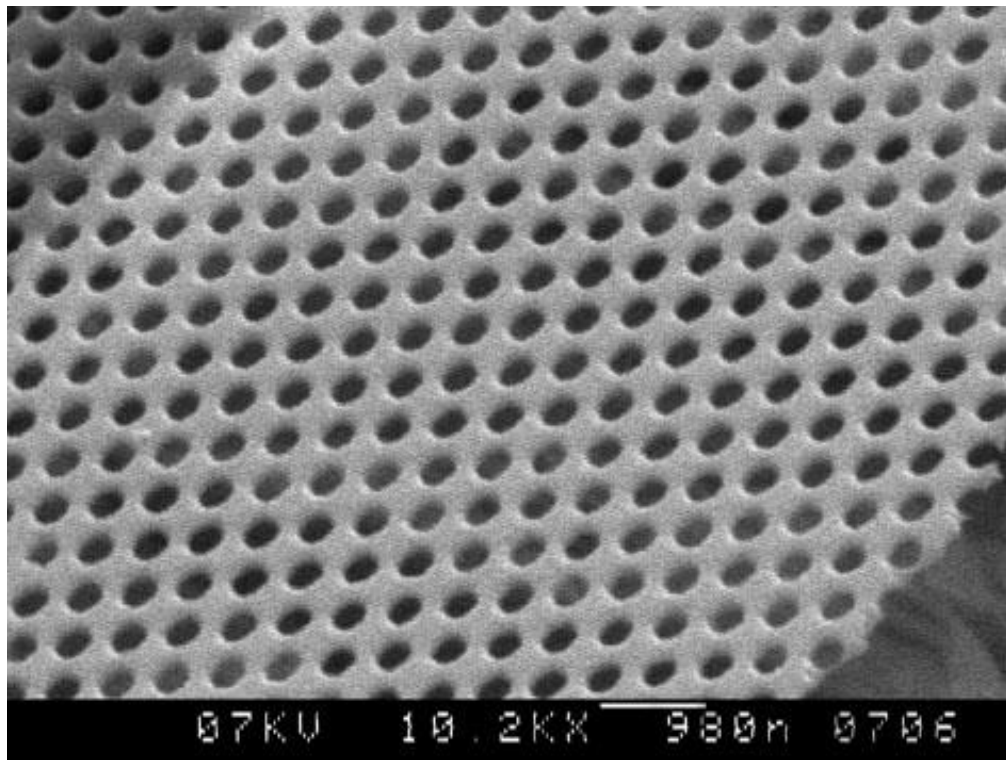
- Vacuum clean
- No resist chemistry
- Fast and simple
- Cost efficient nanofabrication
- Wide choice of material & substrates
- Mainly for PVD, but also ion implantation and dry etching

What are the challenges?

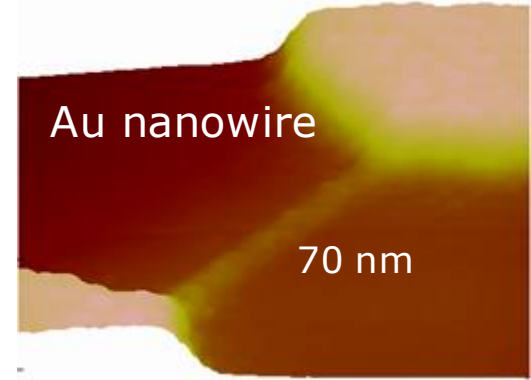
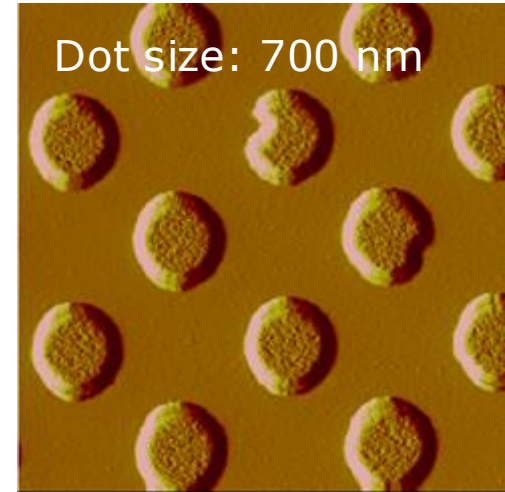
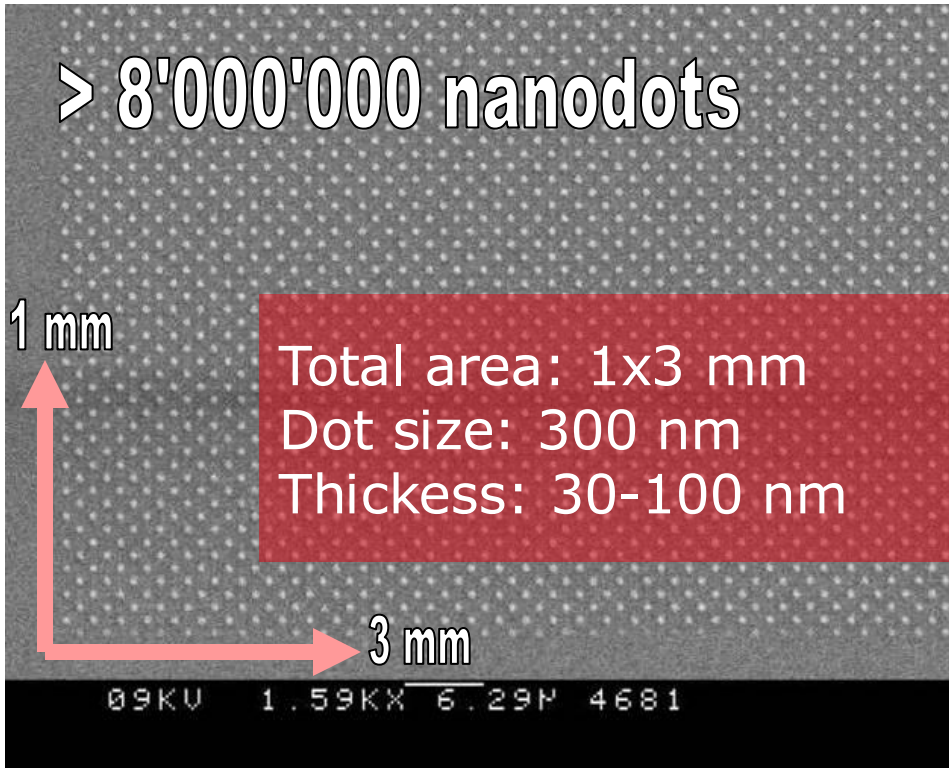
What are the opportunities?



Nanosieves as stencils



Scalable nanostencil ... large membranes



Stencil fabrication

LPCVD 50-500 nm thick SiN

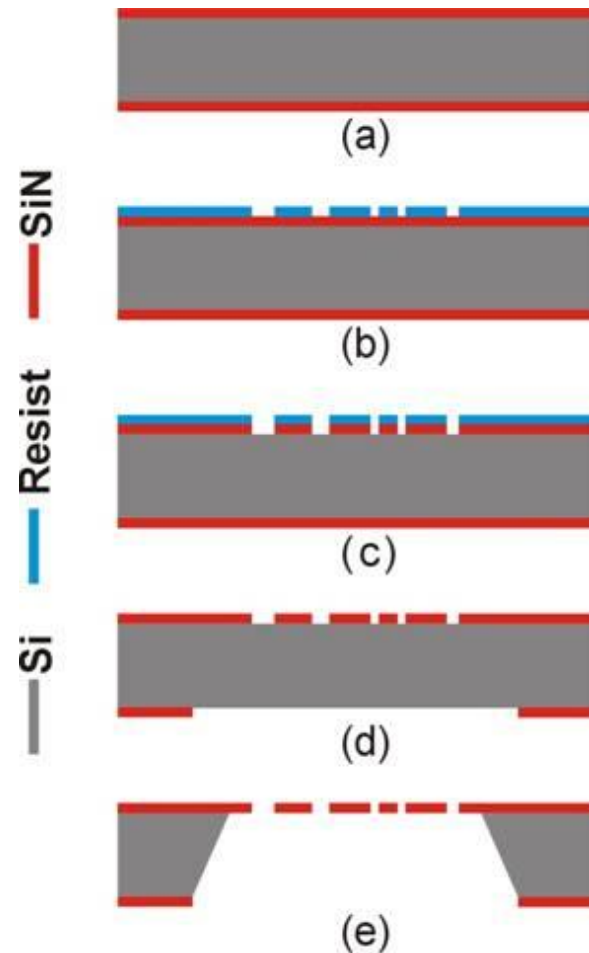
Pattern definition in photoresist

Pattern transfer into SiN

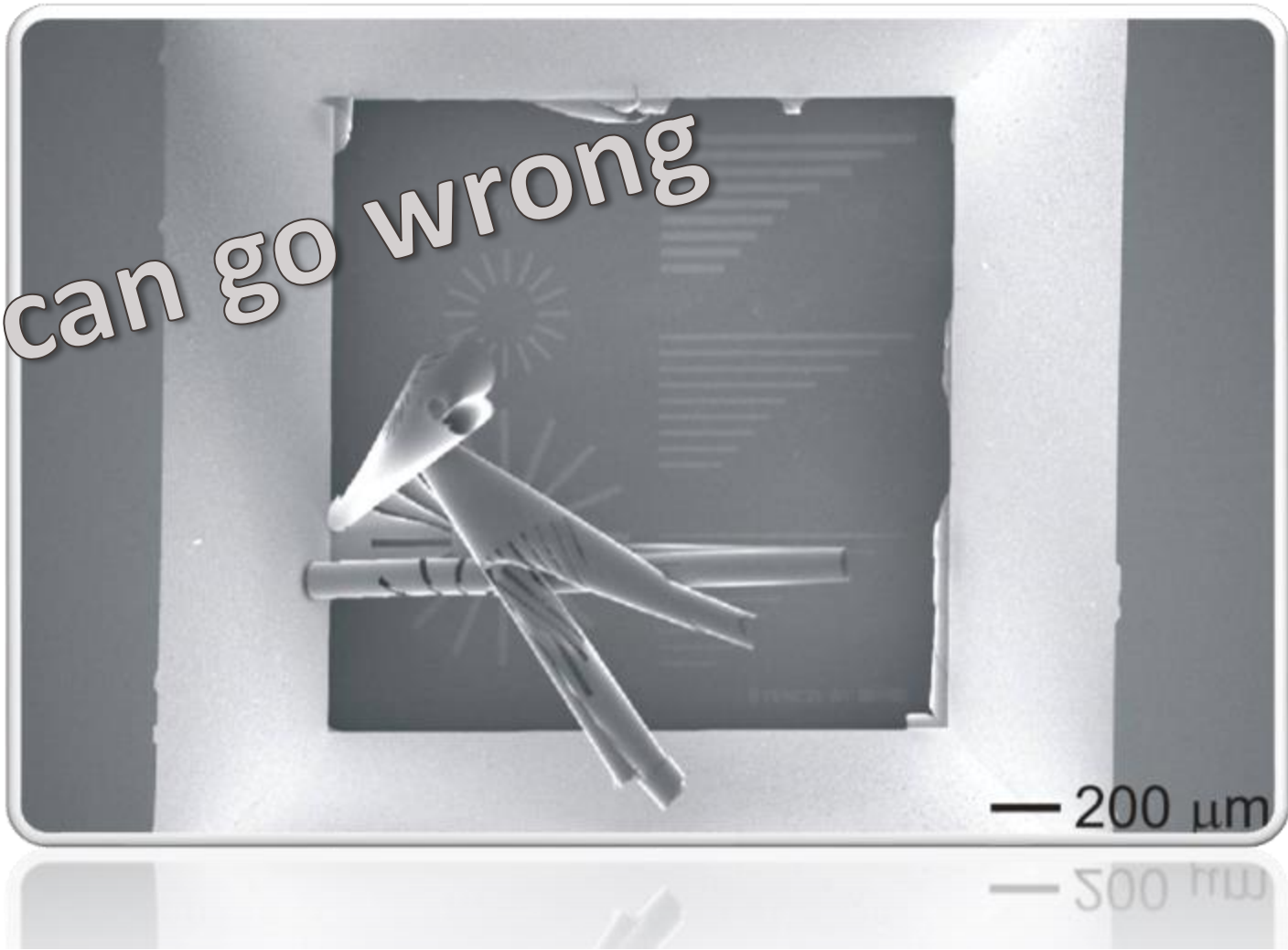
Membrane window definition and KOH etching

Fabrication of nanoscale apertures in membrane by:

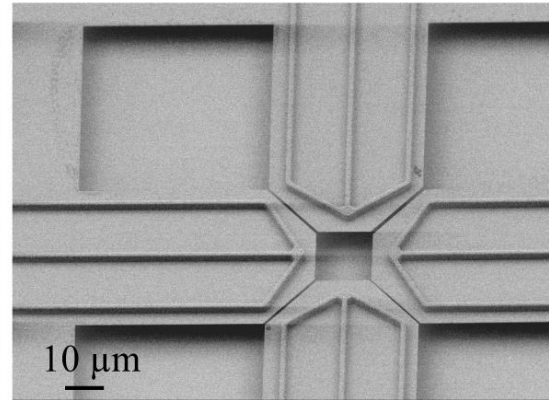
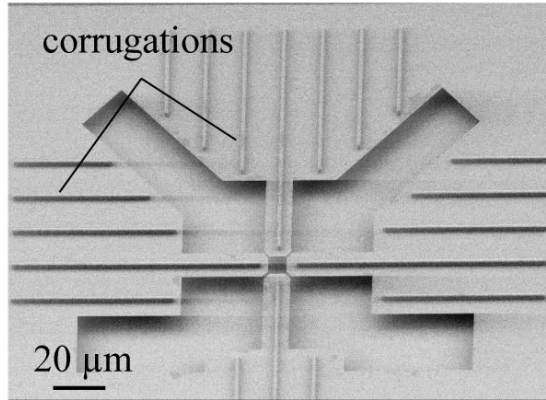
- Focused Ion Beam Milling
- Electron beam lithography
- Laser interference lithography
- Nanoimprint lithography
- Deep UV lithography



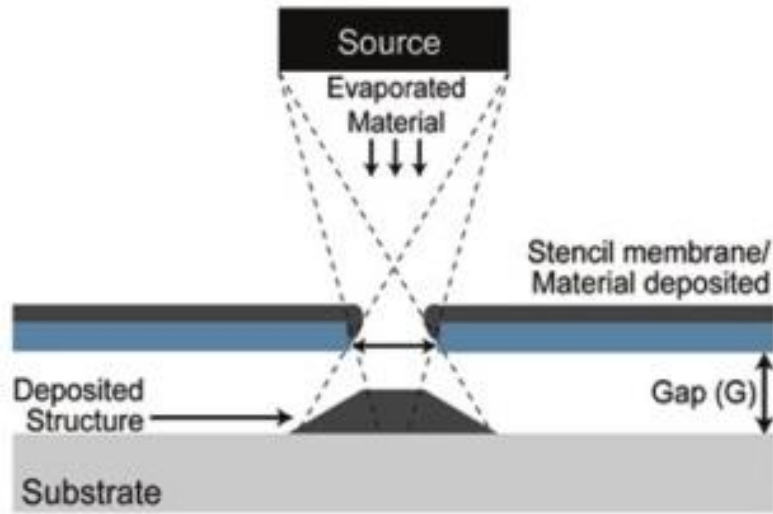
It can go wrong



Increase moment of inertia to stabilize thin membranes

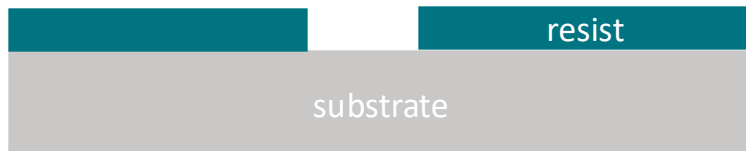


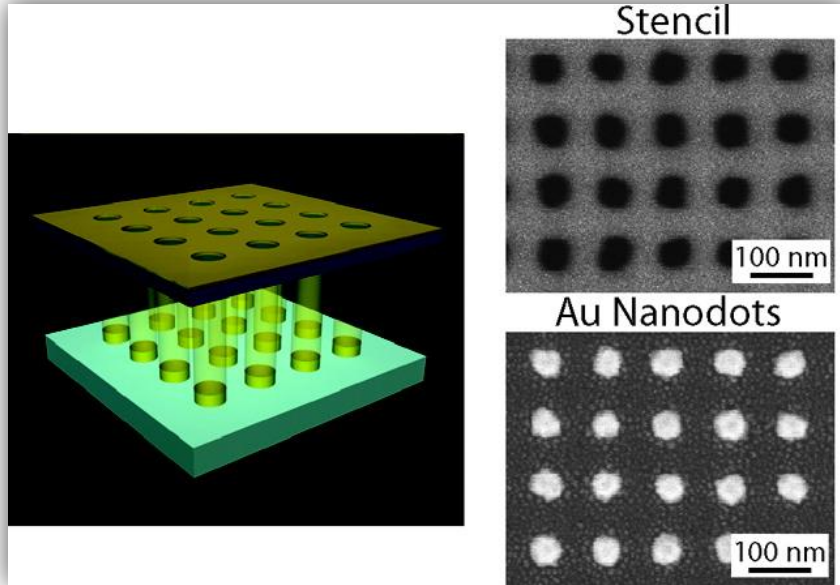
■ Van den Boogaart et al. 2008



Challenge: Gap between stencil and substrate

Compare it to **Lift off**: resist is in contact with substrate; no lateral diffusion

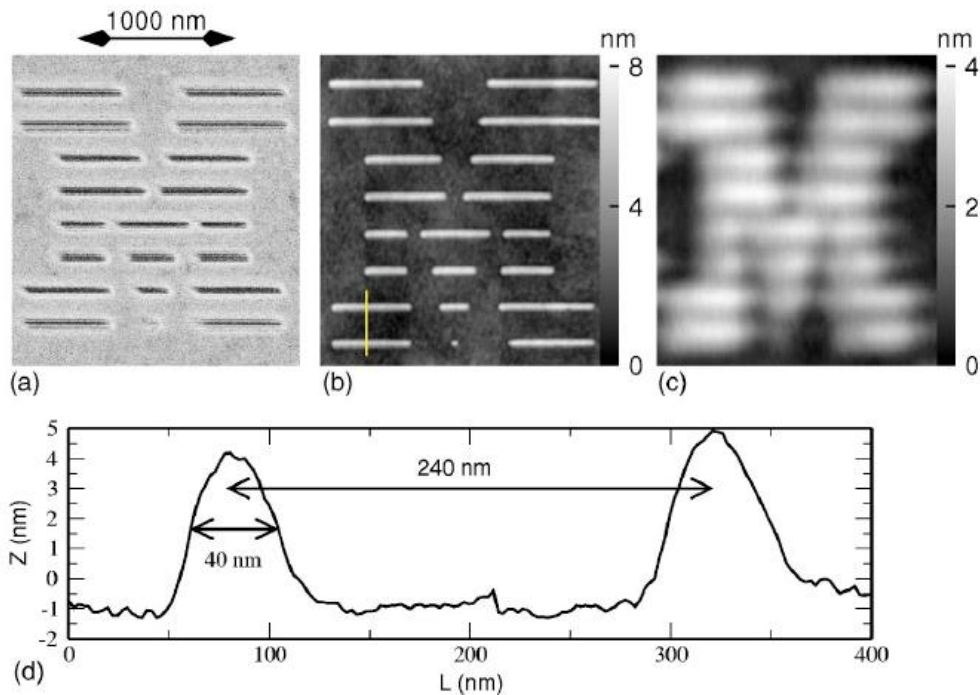




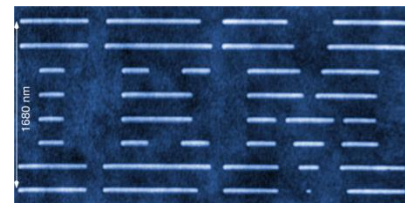
5 nm Ti / 50 nm Au
On Si/SiO₂

Blurring of pattern

Watch out for surface diffusion



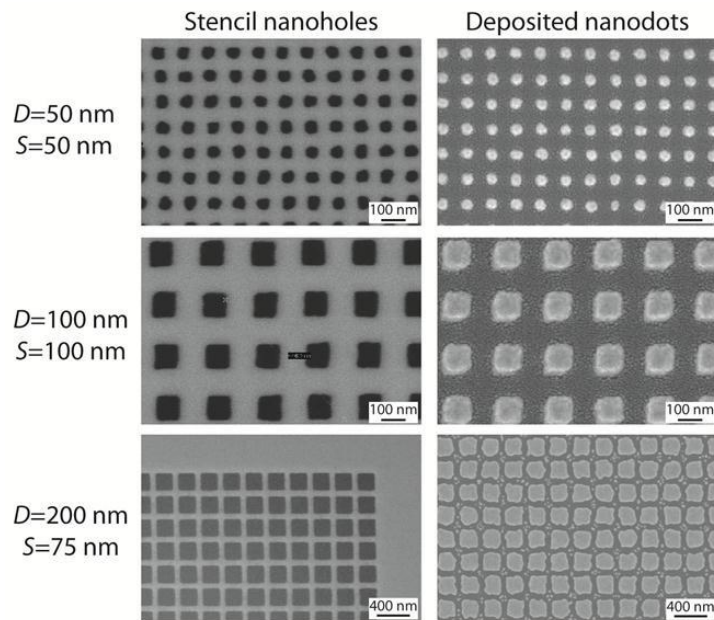
- (a) FIB image of the stencil mask used here
- (b) DFM image of the 40 nm wide Cu structure on SiO₂
- (c) DFM image of the C60 structure (diffusion induced halo).
- (d) Line profile of the section marked.



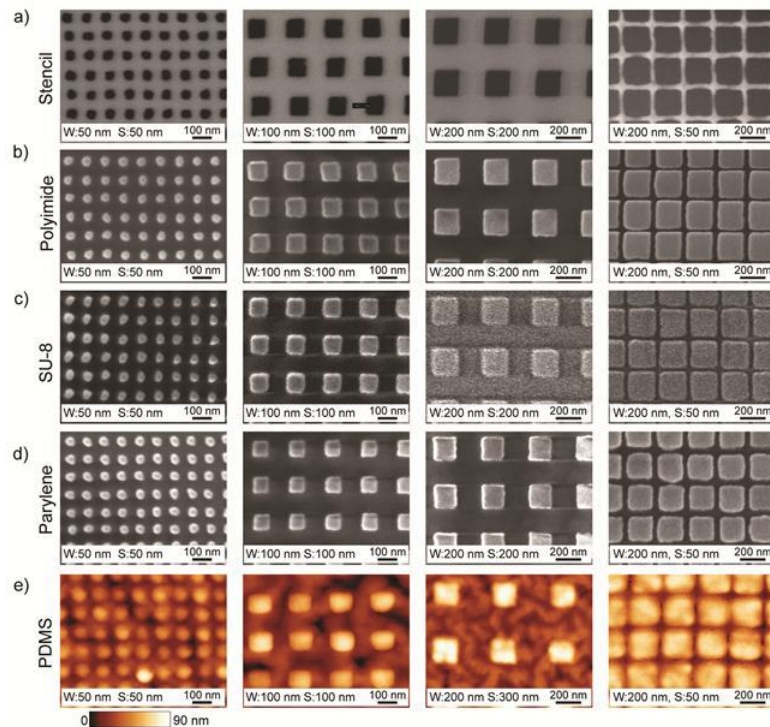
Metallic nanostructures stenciled onto ...

5 nm Ti / 50 nm Au

... **silicon** (Au clusters)



... **polymer** (no Au clusters)

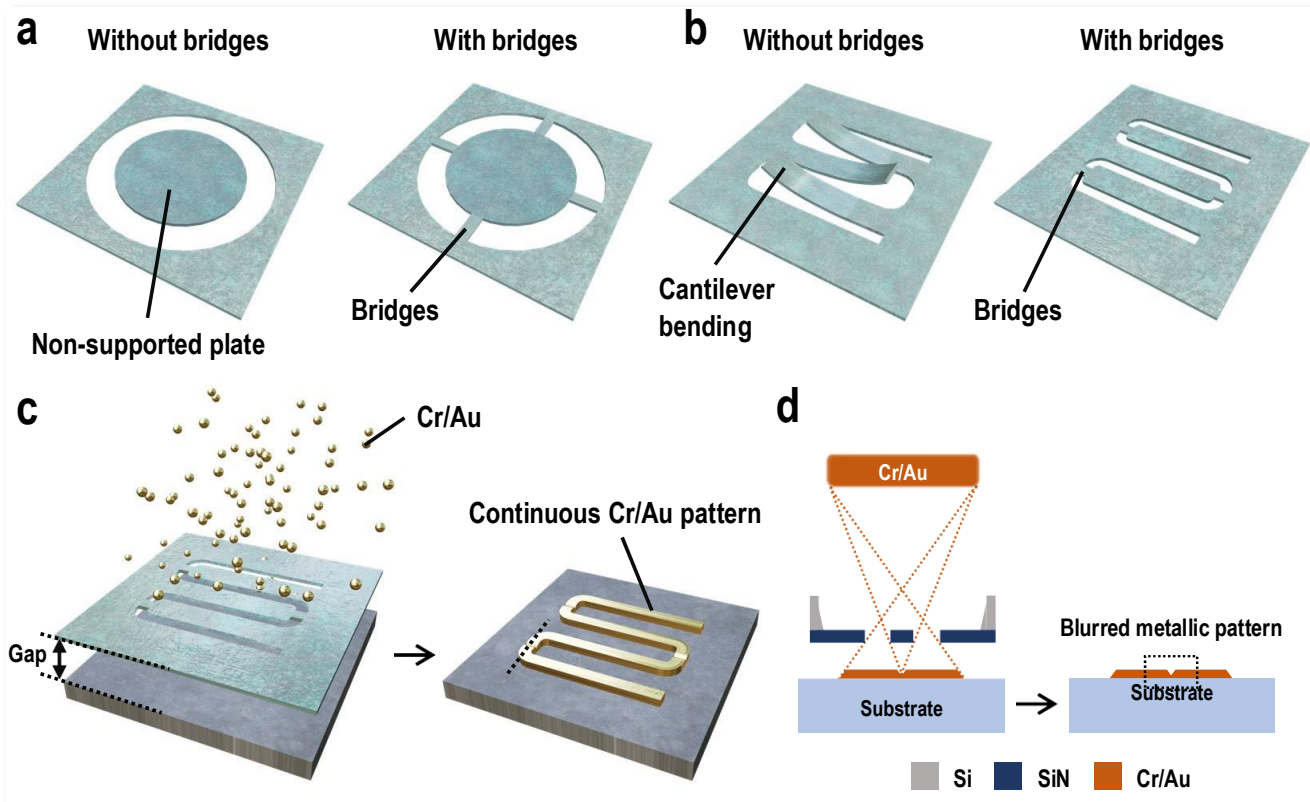




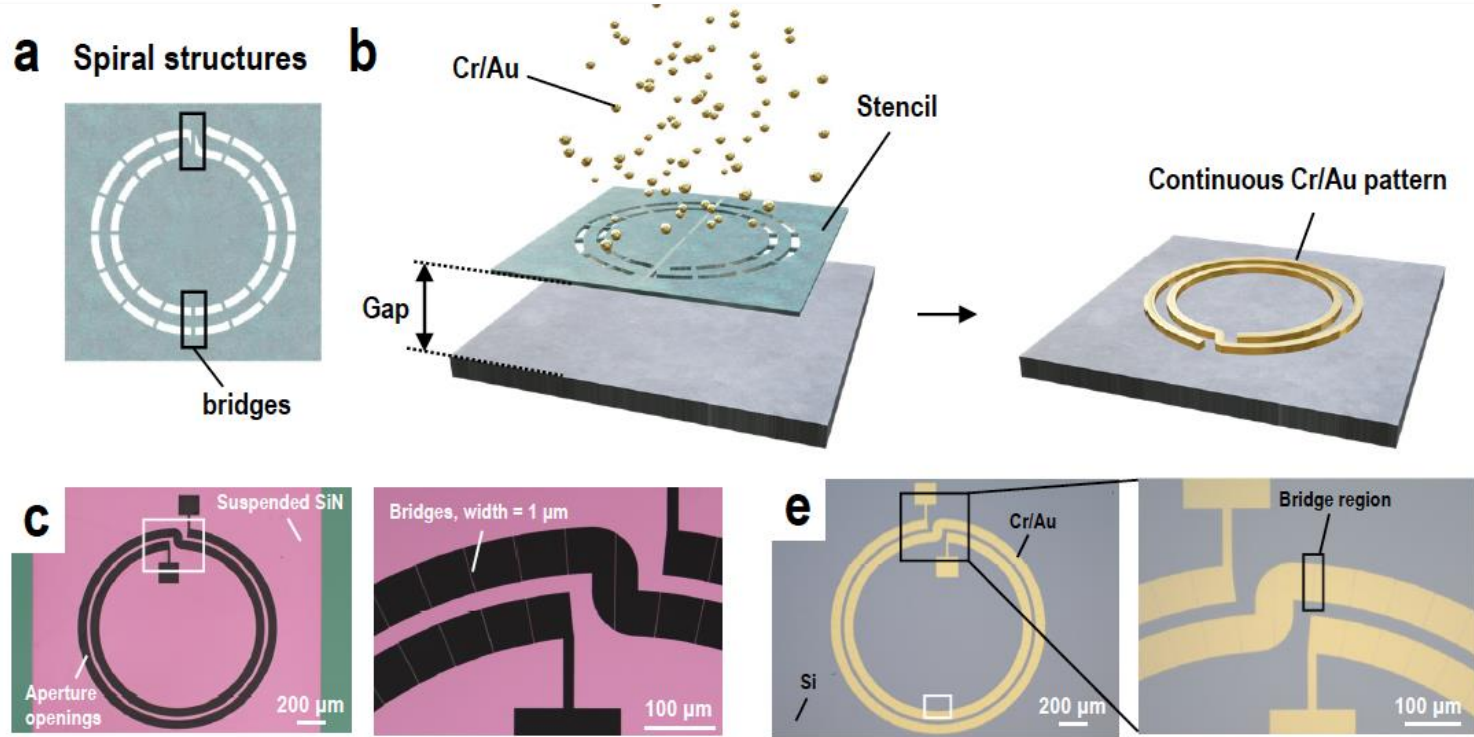
STENCIL

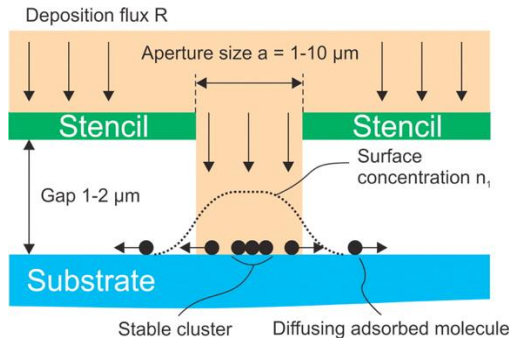
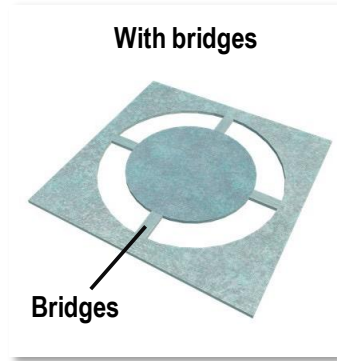
0123456789

Bridge stencils (micro)



Split ring resonator on flexible substrate





Nano stencil lithography

Take home message

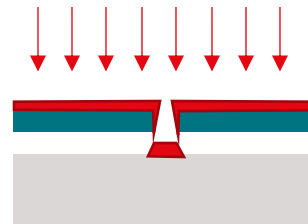
Fast, parallel, scalable patterning without any wet stuff

Vacuum clean interfaces

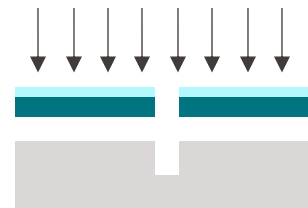
Limits and remedies

Opportunities

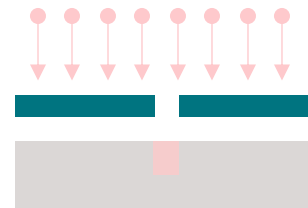
Compare the different stencil applications



Deposition
PVD



Etching
Dry/plasma



Implantation
Ions